



## **IMAPS & IPC to Host On-Shoring Workshop July 10-12, 2023 in Washington, DC**

The International Microelectronics Assembly and Packaging Society (IMAPS) and IPC will host a Workshop to discuss and promote strategies to improve [On-Shoring Advanced Packaging and Assembly](#), July 10-12, 2023, in Washington, DC. This workshop will bring Government agencies, the DIB (Defense Industrial Base) and Advanced Packaging and Assembly providers together to discuss their efforts to onshore advanced packaging. The mission of this event is to engage our workforce community to identify the newly created Advanced Packaging programs which address US Government and Defense requirements critical to the onshoring of the microelectronic assembly and packaging supply chain. Government agencies including the Department of Commerce/NIST, DoD (SHIP/IBAS/Title III/Printed Circuit Board Executive Agent), DARPA and SRC will be briefing on their advanced packaging programs.

Under this new partnership, the IMAPS and IPC leadership will work to expand their efforts around onshoring advanced packaging and assembly, and to build upon each organization's highly successful events held in October 2022. This July workshop will feature two days of focused sessions by invited speakers (Government Agencies, DARPA, DIB, Advanced Packaging and Assembly, Workforce development), a panel discussion, and a variety of networking opportunities.

Keynotes include:

- "CHIPS" – Eric Lin, US Department of Commerce
- "DPA/Title III and ICAM/IBAS Activity" – Anthony Di Stasio, Office of the Under Secretary of Defense (A&S)
- "Next Generation Microelectronics Manufacturing (NGMM)" – Dr. Carl McCants, DARPA
- "DoD ME Commons" – Dr. Dev Shenoy - Office of the Undersecretary of Defense and Director of the Defense Microelectronics Cross Functional Team

The event will kick-off on Monday with a pre-program day filled with 2-hour professional development courses and working groups addressing a variety of topics relevant to the onshoring of advanced packaging.

Technical Chair for the event, Brandon Hamilton with Booz Allen Hamilton stated, "We are excited to bring together packaging and assembly supply chain stakeholders to discuss DoD onshoring initiatives. During the event, attendees will hear from DoD leaders and industry performers on current and future programs and participate in collaborative discussions to inform and address U.S. Government requirements for advanced packaging. This workshop serves as a unique opportunity to interface with multiple levels of Government leadership, the Defense Industrial Base, and Commercial Suppliers, all of whom share a common goal to reshore microelectronics manufacturing."

### **About IMAPS**

IMAPS ([www.imaps.org](http://www.imaps.org)) is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, packaging organizations, and students through technical conferences and workshops, professional development courses, a microelectronics packaging research library, local chapters and exhibitions. The Society encompasses a wide-range of technologies critical to microelectronics assembly and packaging, including: on-shoring, heterogenous integration, fan-out wafer level packaging, 2.5D/3D technologies, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

### **About IPC**

IPC ([www.IPC.org](http://www.IPC.org)) is a global industry association based in Bannockburn, Ill., dedicated to the competitive excellence and financial success of its 3,100+ member companies which represent all facets of the electronics industry, including design, printed board manufacturing, electronics assembly, and test. As a member-driven organization and leading source for industry standards, training, market research and public policy advocacy, IPC supports programs to meet the needs of an estimated \$2 trillion global electronics industry.

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